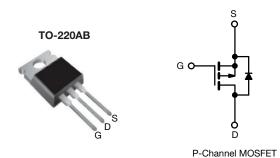
Vishay Siliconix



## **Power MOSFET**



| PRODUCT SUMM             | ARY                     |      |
|--------------------------|-------------------------|------|
| V <sub>DS</sub> (V)      | -60                     | )    |
| $R_{DS(on)}(\Omega)$     | V <sub>GS</sub> = -10 V | 0.28 |
| Q <sub>g</sub> max. (nC) | 19                      | 1    |
| Q <sub>gs</sub> (nC)     | 5.4                     | 1    |
| Q <sub>gd</sub> (nC)     | 11                      |      |
| Configuration            | Sing                    | ıle  |

#### **FEATURES**

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

## **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

| ORDERING INFORMATION            |                |
|---------------------------------|----------------|
| Package                         | TO-220AB       |
| Lead (Pb)-free                  | IRF9Z24PbF     |
| Lead (Pb)-free and halogen-free | IRF9Z24PbF-BE3 |

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>                  | = 25 °C, unle           | ess otherwis  | e noted)                          |             |          |  |
|---|-------------------------|---|-----------------------------------|-------------|----------|--|
| PARAMETER   |                         | SYMBOL  | LIMIT                             | UNIT        |          |  |
| Drain-source voltage                                      |                         |   | $V_{DS}$                          | -60         | V        |  |
| Gate-source voltage                                       |                         |   | $V_{GS}$                          | ± 20        | _ V      |  |
| Continuous dusin surrent                                  | \/ at 10\/              | $T_{\rm C} = 25  ^{\circ}{\rm C}$<br>$T_{\rm C} = 100  ^{\circ}{\rm C}$ |                                   | -11         |          |  |
| Continuous drain current                                  | V <sub>GS</sub> at 10 V | T <sub>C</sub> = 100 °C   | I <sub>D</sub>                    | -7.7        | Α        |  |
| Pulsed drain current a                                    |                         |   | I <sub>DM</sub>                   | -44         |          |  |
| Linear derating factor                                    |                         |   |                                   | 0.40        | W/°C     |  |
| Single pulse avalanche energy b                           |                         |   | E <sub>AS</sub>                   | 240         | mJ       |  |
| Repetitive avalanche current a                            |                         |   | I <sub>AR</sub>                   | -11         | A        |  |
| Repetitive avalanche energy <sup>a</sup>                  |                         |   | E <sub>AR</sub>                   | 6.0         | mJ       |  |
| Maximum power dissipation $T_C = 25  ^{\circ}C$           |                         | 25 °C   | $P_{D}$                           | 60          | W        |  |
| Peak diode recovery dV/dt <sup>c</sup>                    |                         |   | dV/dt                             | -4.5        | V/ns     |  |
| Operating junction and storage temperature range          |                         |   | T <sub>J</sub> , T <sub>stg</sub> | -55 to +175 |          |  |
| Soldering recommendations (peak temperature) <sup>d</sup> | For                     | 10 s  |                                   | 300         | °C       |  |
| Maunting tours  | 6-32 or N               | 10 corour   |                                   | 10          | lbf ⋅ in |  |
| Mounting torque   | 0-32 Of N               | no sciew  |                                   | 1.1         | N⋅m      |  |

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b.  $V_{DD} = -25 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 2.3 \,\text{mH}$ ,  $R_g = 25 \,\Omega$ ,  $I_{AS} = -11 \,\text{A}$  (see fig. 12)
- c.  $I_{SD} \le -11$  A,  $dI/dt \le 140$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175$  °C
- d. 1.6 mm from case



# Vishay Siliconix

| THERMAL RESISTANCE RAT              | INGS              |      |      |      |
|-------------------------------------|-------------------|------|------|------|
| PARAMETER                           | SYMBOL            | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient         | R <sub>thJA</sub> | -    | 62   |      |
| Case-to-sink, flat, greased surface | R <sub>thCS</sub> | 0.50 | -    | °C/W |
| Maximum junction-to-case (drain)    | R <sub>thJC</sub> | -    | 2.5  |      |

| PARAMETER                                 | SYMBOL                | TEST CONDITIONS   |   | MIN.     | TYP.      | MAX.                 | UNIT             |
|---|-----------------------|---|---|----------|-----------|----------------------|------------------|
| Static                                    |                       |   |   |          |           |                      |                  |
| Drain-source breakdown voltage            | V <sub>DS</sub>       | $V_{GS} = 0$  | Ο V, I <sub>D</sub> = -250 μA   | -60      | -         | -                    | V                |
| V <sub>DS</sub> temperature coefficient   | $\Delta V_{DS}/T_{J}$ | Reference   | to 25 °C, I <sub>D</sub> = -1 mA  | =        | -0.056    | -                    | V/°C             |
| Gate-source threshold voltage             | V <sub>GS(th)</sub>   | V <sub>DS</sub> = \   | / <sub>GS</sub> , I <sub>D</sub> = -250 μA                                      | -2.0     | -         | -4.0                 | V                |
| Gate-source leakage                       | I <sub>GSS</sub>      | V   | <sub>GS</sub> = ± 20 V  | -        | -         | ± 100                | nA               |
| Zero gate voltage drain current           | I <sub>DSS</sub>      |   | -60 V, V <sub>GS</sub> = 0 V<br>V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C  |          | -         | -100<br>-500         | μА               |
| Drain-source on-state resistance          | R <sub>DS(on)</sub>   | V <sub>GS</sub> = -10 V   | I <sub>D</sub> = -6.6 A <sup>b</sup>  | =        | -         | 0.28                 | Ω                |
| Forward transconductance                  | 9 <sub>fs</sub>       | V <sub>DS</sub> = -2  | 25 V, I <sub>D</sub> = -6.6 A <sup>b</sup>                                      | 1.4      | -         | -                    | S                |
| Dynamic                                   |                       | •   |   |          |           |                      |                  |
| Input capacitance                         | C <sub>iss</sub>      | $V_{GS} = 0 V$ ,  |   | =-       | 570       | -                    |                  |
| Output capacitance                        | C <sub>oss</sub>      | V   | DS = -25  V,  | -        | 360       | -                    | рF               |
| Reverse transfer capacitance              | C <sub>rss</sub>      | f = 1.0 MHz, see fig. 5   |   | =        | 65        | -                    |                  |
| Total gate charge                         | Qg                    |   | I <sub>D</sub> = -11 A, V <sub>DS</sub> = -48 V, see fig. 6 and 13 <sup>b</sup> | -        | =         | 19                   | nC               |
| Gate-source charge                        | Q <sub>gs</sub>       | $V_{GS} = -10 \text{ V}$  |   | =.       | -         | 5.4                  |                  |
| Gate-drain charge                         | Q <sub>gd</sub>       |   |   | =        | -         | 11                   |                  |
| Turn-on delay time                        | t <sub>d(on)</sub>    |   |   | =.       | 13        | -                    |                  |
| Rise time                                 | t <sub>r</sub>        | $V_{DD}$ = -30 V, $I_{D}$ = -11 A, $R_{g}$ = 18 $\Omega$ , $R_{D}$ = 2.5 $\Omega$ , see fig. 10 b |   | =.       | 68        | -                    | ns               |
| Turn-off delay time                       | t <sub>d(off)</sub>   |   |   | -        | 15        | -                    |                  |
| Fall time                                 | t <sub>f</sub>        |   |   | -        | 29        | -                    |                  |
| Gate input resistance                     | R <sub>g</sub>        | f = 1 MHz, open drain   |   | 0.5      | -         | 3.5                  | Ω                |
| Internal drain inductance                 | L <sub>D</sub>        | 6 mm (0.25")  | Between lead,<br>6 mm (0.25") from  |          | 4.5       | -                    | 11               |
| Internal source inductance                | L <sub>S</sub>        | package and center of die contact   |   | -        | 7.5       | -                    | nH               |
| Drain-Source Body Diode Characteristic    | es                    |   |   |          |           |                      |                  |
| Continuous source-drain diode current     | I <sub>S</sub>        | MOSFET symbol showing the integral reverse p - n junction diode                                   |   | ı        | -         | -11                  | - A              |
| Pulsed diode forward current <sup>a</sup> | I <sub>SM</sub>       |   |   | -        | -         | -44                  |                  |
| Body diode voltage                        | V <sub>SD</sub>       | T <sub>J</sub> = 25 °C, I <sub>S</sub> = -11 A, V <sub>GS</sub> = 0 V b                           |   | -        | -         | -6.3                 | V                |
| Body diode reverse recovery time          | t <sub>rr</sub>       | - T <sub>J</sub> = 25 °C, I <sub>F</sub> = -11 A, dl/dt = 100 A/μs b                              |   | -        | 100       | 200                  | ns               |
| Body diode reverse recovery charge        | Q <sub>rr</sub>       |   |   | -        | 0.32      | 0.64                 | μC               |
| Forward turn-on time                      | t <sub>on</sub>       | Intrinsic turi  | n-on time is negligible (turn   | on is do | minated b | y L <sub>S</sub> and | L <sub>D</sub> ) |

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

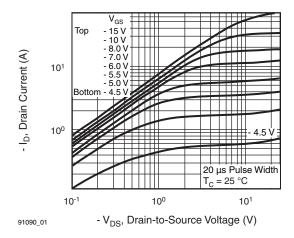


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

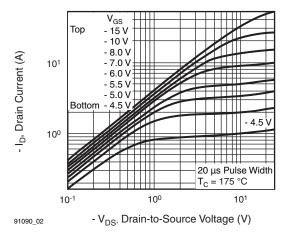


Fig. 2 - Typical Output Characteristics,  $T_C = 175$  °C

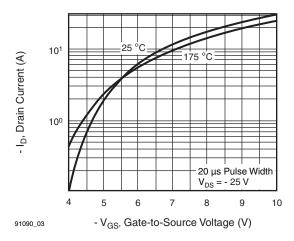


Fig. 3 - Typical Transfer Characteristics

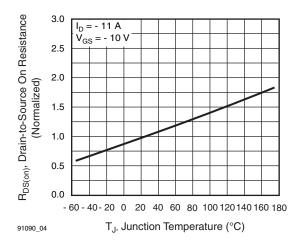


Fig. 4 - Normalized On-Resistance vs. Temperature

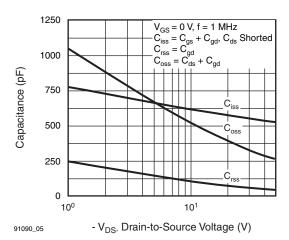


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

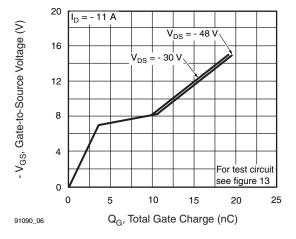


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



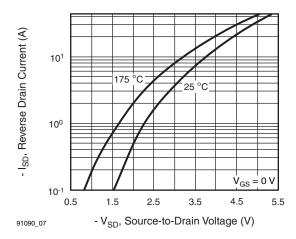


Fig. 7 - Typical Source-Drain Diode Forward Voltage

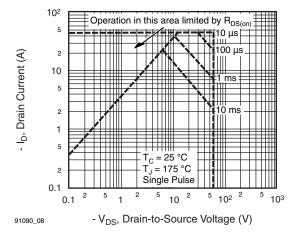


Fig. 8 - Maximum Safe Operating Area

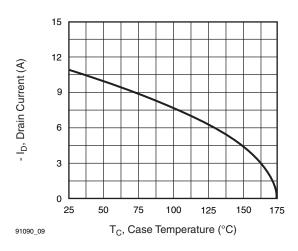


Fig. 9 - Maximum Drain Current vs. Case Temperature

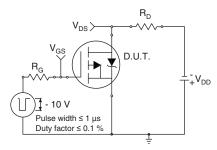


Fig. 10a - Switching Time Test Circuit

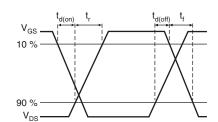


Fig. 10b - Switching Time Waveforms

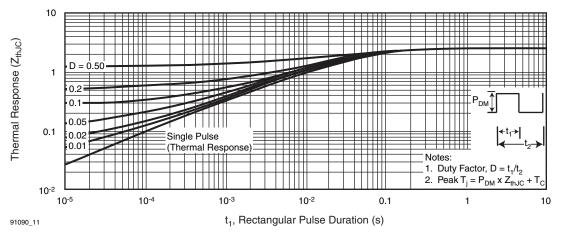


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



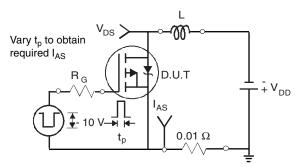


Fig. 12a - Unclamped Inductive Test Circuit

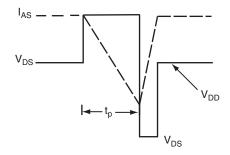


Fig. 12b - Unclamped Inductive Waveforms

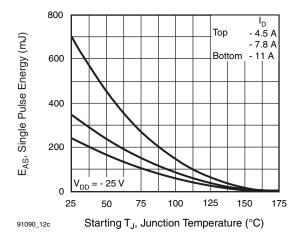


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

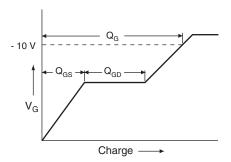


Fig. 13a - Basic Gate Charge Waveform

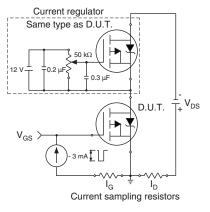
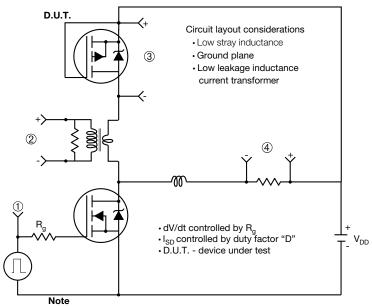


Fig 13b - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

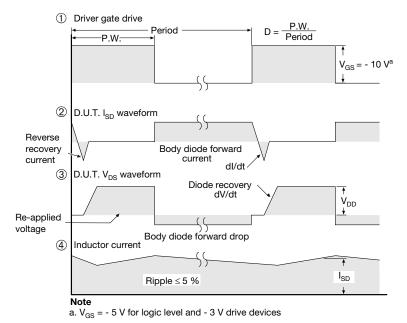
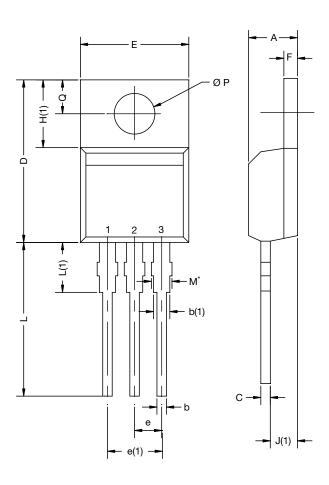


Fig. 14 - For P-Channel

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# TO-220-1



| DIM. | MILLIM | IETERS | INC   | HES   |
|------|--------|--------|-------|-------|
|      | MIN.   | MAX.   | MIN.  | MAX.  |
| Α    | 4.24   | 4.65   | 0.167 | 0.183 |
| b    | 0.69   | 1.02   | 0.027 | 0.040 |
| b(1) | 1.14   | 1.78   | 0.045 | 0.070 |
| С    | 0.36   | 0.61   | 0.014 | 0.024 |
| D    | 14.33  | 15.85  | 0.564 | 0.624 |
| Е    | 9.96   | 10.52  | 0.392 | 0.414 |
| е    | 2.41   | 2.67   | 0.095 | 0.105 |
| e(1) | 4.88   | 5.28   | 0.192 | 0.208 |
| F    | 1.14   | 1.40   | 0.045 | 0.055 |
| H(1) | 6.10   | 6.71   | 0.240 | 0.264 |
| J(1) | 2.41   | 2.92   | 0.095 | 0.115 |
| L    | 13.36  | 14.40  | 0.526 | 0.567 |
| L(1) | 3.33   | 4.04   | 0.131 | 0.159 |
| ØΡ   | 3.53   | 3.94   | 0.139 | 0.155 |
| Q    | 2.54   | 3.00   | 0.100 | 0.118 |

#### Note

DWG: 6031

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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